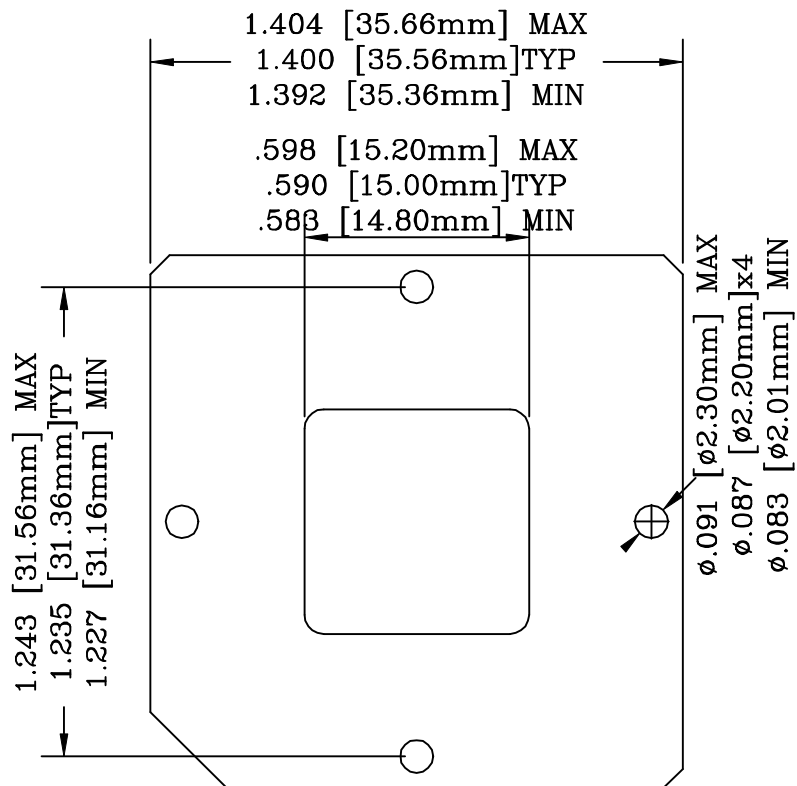


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	2/14/01	A.F.

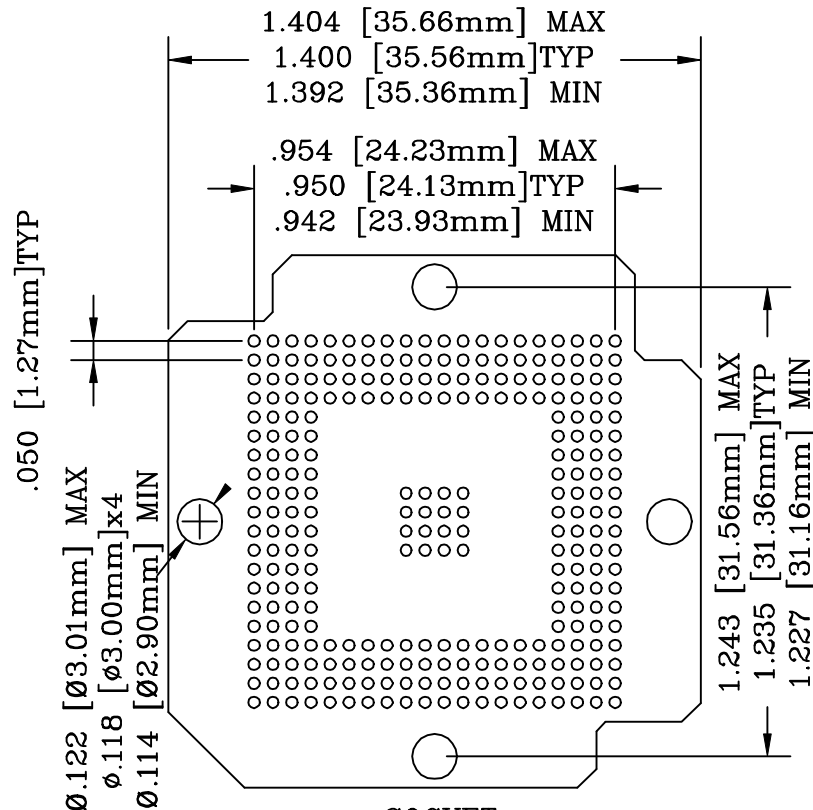
SCALE 2:1

SKT818

DOD 4818



RETENTION FRAME

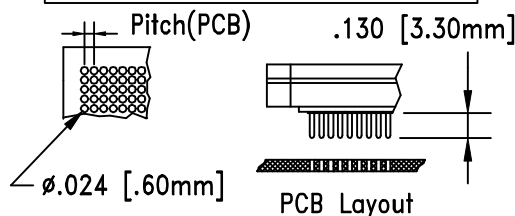
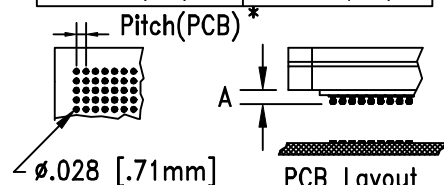


SOCKET

RECOMMENDED PAD LAYOUT

SOLDERTAIL STYLE	
REGULAR SMT STYLE	RAISED SMT STYLE
XX = (-SM)	XX = (-RC)
YY = (-30)	YY = (-29)

SOLDERTAIL = THRU HOLE STYLE
XX = (-ET)
YY = (-70)



30= standard SMD ("A" = .047 [1.20mm])
29= raised SMD ("A" = .197 [5.00mm])

BALL DIAMETER FOR:
-29(RC) = .026 [0.66mm]
-30(SM) = .026 [0.66mm]

PIN DIAMETER FOR:
-70(ET) = .018 [0.45mm]

* The pitch dimension depends on your Ball Grid Array Package

PACKAGE SPECIFICATIONS

PIN COUNT	= 272
LEAD PITCH	= 1.27mm
GRID SIZE	= 20x20
PACKAGE SIZE	= 27.00mm SQUARE

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



Emulation Technology, Inc.

— VLSI and SMT ADAPTERS and ACCESSORIES —

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Santa Clara, Ca 95051

TEL:(408)982-0660
FAX:(408)982-0664

SHEET:
1 OF 1

DATE:
2/14/01

REVISION:

ASSEMBLY DRAWING

CHECKED:
Perry Munroe

DRAWN:
Aaron Fine

ITEM: S-BGA-20-272-XX

DESCRIPTION:
BPW-272-2BG020-YY

DO NOT SCALE DRAWING